

ENGINEERING	RELIABILITY TEST REPORT	SPEC.NO.: SPCH060A
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TEST ITEM :1.ELECTRICAL  
2.MECHANICAL  
3.ENVIRONMENTAL

TEST EQUIPMENT :1.INSERTION & REMOVAL APPARATUS  
2.ELECTRONIC MEASURING APPARATUS  
3.ENVIRONMENTAL APPARATUS

SERIES NO. : CH60\*\*2SA00-T0

DATE OF TESTING : 2015/03/31

TEST DEPART : R & D

LOT Number:

CONTAIN :

TEST RESULT: ACCEPT REJECT



APPROVE BY: *Eisley*

CHECKED By: *Eisley*

TESTER BY: *Sandy*

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**1.ELECTRICAL PERFORMANCE :**

	ITEM	TEST CONDITION	REQUIREMENT	TEST RESULT	
1-1	Rated current and voltage		1A 250V AC (r.m.s)		
1-2	Contact resistance	Meted connector, Contact: measured by dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ	Sample	20 mΩ Max.
				1	10.4 mΩ
				2	10.2 mΩ
				3	10.8 mΩ
				4	10.6 mΩ
				5	11.0 mΩ
1-3	Dielectric strength	When applied AC 500V 1 minute between adjacent terminal	No breakdown	Sample	1 minute
				1	Pass
				2	Pass
				3	Pass
				4	Pass
				5	Pass
1-4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 5000 MΩ	Sample	5000 MΩ min.
				1	10×10 <sup>6</sup> MΩ
				2	10×10 <sup>6</sup> MΩ
				3	10×10 <sup>6</sup> MΩ
				4	10×10 <sup>6</sup> MΩ
				5	10×10 <sup>6</sup> MΩ

**2. MECHANICAL PERFORMANCE :**

	ITEM	TEST CONDITION	REQUIREMENT	TEST RESULT	
2-1	Pin retention force	Push pin from insulator base at speed 25±3mm per minute	More than 400gram	Sample	400gram min.
				1	1.75 Kgf
				2	1.39 Kgf
				3	2.00 Kgf
				4	1.57 Kgf
				5	1.60 Kgf

**3.ENVIRONMENTAL PERFORMANCE:**

	ITEM	TEST CONDITION	REQUIREMENT	TEST RESULT	
3-1	Solder ability	Soldering time:3±0.5 second Soldering pot: 245 ± 5 °C	Minimum: 90% of immersed area	Sample	> 90%
				1	Pass
				2	Pass
				3	Pass
				4	Pass
				5	Pass

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	ITEM	TEST CONDITION	REQUIREMENT	TEST RESULT	
				Sample	
3-2	Resistance to soldering heat	Lead-Free Process for SMT Type: Refer Reflow temperature profile(5-1)	No damage		No damage
				1	Pass
				2	Pass
				3	Pass
				4	Pass
				5	Pass
3-3	Heat aging	105±2°C , 96 hours	Appearance: No damage		No damage
				1	Pass
				2	Pass
				3	Pass
				4	Pass
				5	Pass
3-4	Humidity	40 ±2°C, 90-95%RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage		No damage
				1	Pass
				2	Pass
				3	Pass
				4	Pass
				5	Pass
3-5	Temperature cycling	One cycle consists of: 1. -40 <sup>+0</sup> -3 °C, 30 min. 2. Room temp. 10-15 min. 3. 85 <sup>+3</sup> -0 °C, 30 min. 4. Room temp. 10-15 min.	Appearance: No damage		No damage
				1	Pass
				2	Pass
				3	Pass
				4	Pass
				5	Pass

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ITEM	TEST CONDITION	REQUIREMENT	TEST RESULT	
			Sample	No damage
3-6	Salt spray Temperature:35±3°C Solution:5±1% Spray time:8±4 hours Measurement must be taken after water rinse	Appearance: No damage	1	Pass
			2	Pass
			3	Pass
			4	Pass
			5	Pass
			5	Pass

4. AMBIENT TEMPERATURE RANGE : -40 to + 105°C

5. Recommended IR Reflow Temperature Profile:

5-1 Using Lead-Free Solder Paste

